

N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- Optimized body diode reverse recovery performance
- •Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

♦ Intrinsic fast-recovery body diode

710

62

45

65

D

S

Schematic diagram

VDS min@Tjmax

GC

RDS(ON)TYP

ID

Qg

V

mΩ

А

nC

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65TF078T	TO-247	NCE65TF078T

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	VDS	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	45	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	28.3	A
Pulsed drain current ^(Note 1)	I _{DM (pluse)}	135	A
Maximum Power Dissipation(Tc=25°C)	PD	400	W
Derate above 25°C		3.2	W/°C
Single pulse avalanche energy ^(Note 2)	Eas	907	mJ
Avalanche current ^(Note 1)	I _{AR}	11	A
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} ^(Note 1)	E _{AR}	0.9	mJ
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+150	°C

* limited by maximum junction temperature



TO-247



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.31	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	RthJA	62	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =500µA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2.5	3.5	4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =23A		62	78	mΩ
Dynamic Characteristics	'					
Input Capacitance	Clss			4000	4400	pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V, F=1.0MHz		240		pF
Reverse Transfer Capacitance	Crss	F=1.0MHZ		1.1		pF
Total Gate Charge	Qg			65	75	nC
Gate-Source Charge	Q _{gs}	V _{DS} =480V,I _D =23A,		24		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		15		nC
Gate plateau voltage	Vgp			6		V
Intrinsic gate resistance	R _G	f = 1 MHz open drain		10.5		Ω
Switching times				·		
Turn-on Delay Time	t _{d(on)}			16		nS
Turn-on Rise Time	tr	V _{DD} =380V,I _D =23A,		13		nS
Turn-Off Delay Time	t _{d(off)}	R _G =1.7Ω,V _{GS} =10V		71		nS
Turn-Off Fall Time	t _f			13		nS
Source- Drain Diode Characteristics				·	•	
Source-drain current(Body Diode)	I _{SD}	T -05%0			45	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _c =25°C			135	Α
Forward On Voltage	Vsd	Tj=25°C,I _{SD} =45A,V _{GS} =0V 0.9		0.9	1.2	V
Reverse Recovery Time	t _{rr}			180		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=23A,di/dt=100		1.6		uC
Peak Reverse Recovery Current	Irrm	A/µs		18		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^\circ \!\! ^\circ \!\! ^$



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

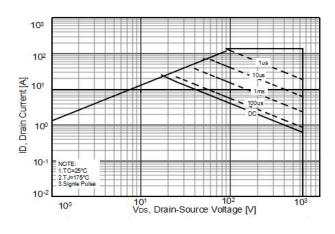


Figure1. Safe operating area

Figure3. Source-Drain Diode Forward Voltage

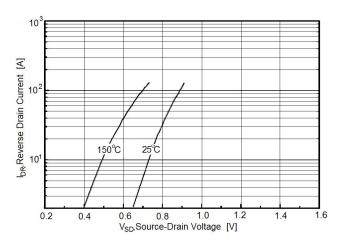


Figure 5. Transfer characteristics

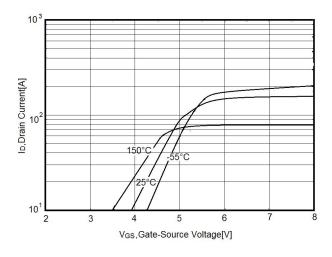


Figure2. Capacitance

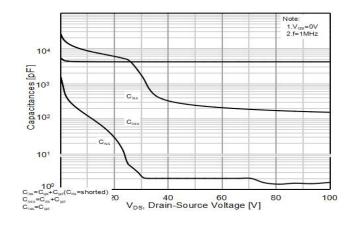


Figure4. Output characteristics

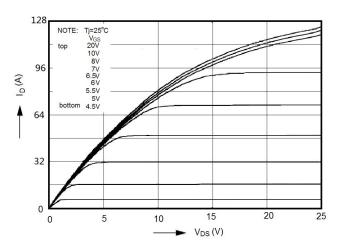


Figure6. Static drain-source on resistance

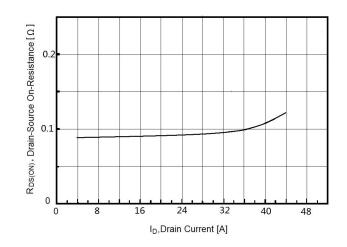






Figure7. R_{DS(ON)} vs Junction Temperature

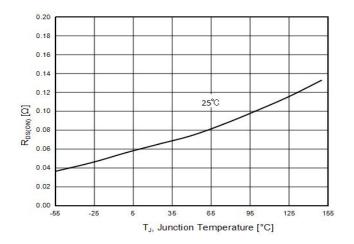


Figure9. Maximum I_D vs Junction Temperature

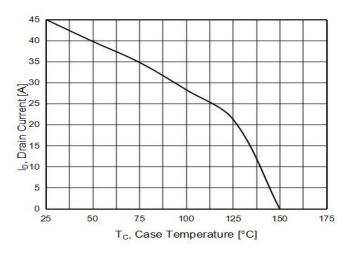


Figure8. BV_{DSS} vs Junction Temperature

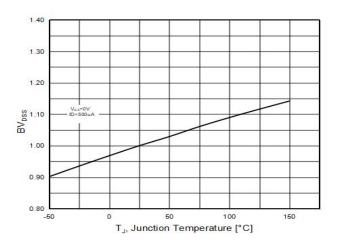
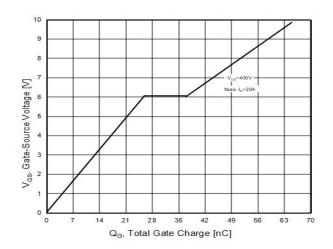


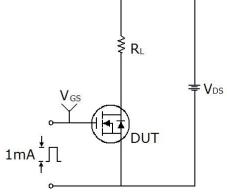
Figure10. Gate charge waveforms

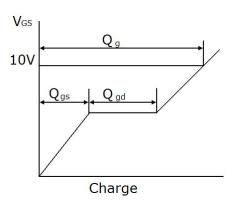




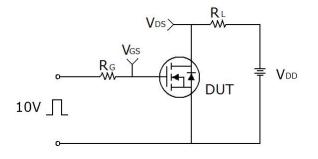
Test circuit

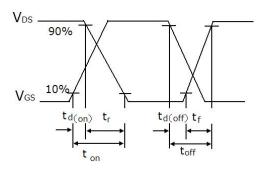
1) Gate charge test circuit & Waveform



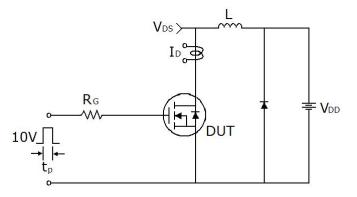


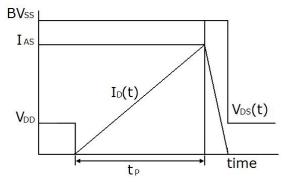
2) Switch Time Test Circuit:





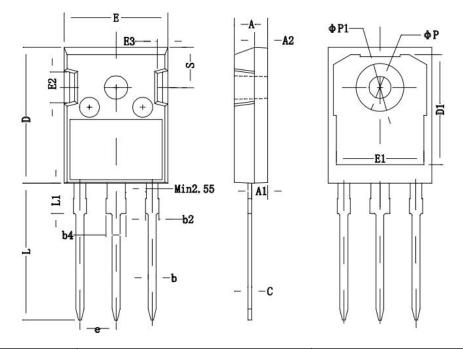
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-247 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
А	4.80	5.20	0.19	0.20
A1	2.21	2.59	0.09	0.10
A2	1.85	2.15	0.07	0.08
b	1.11	1.36	0.04	0.05
b2	1.91	2.21	0.08	0.09
b4	2.91	3.21	0.11	0.13
С	0.51	0.75	0.02	0.03
D	20.80	21.30	0.82	0.84
D1	16.25	16.85	0.64	0.66
E	15.50	16.10	0.61	0.63
E1	13.00	13.60	0.51	0.54
E2	4.80	5.20	0.19	0.20
E3	2.30	2.70	0.09	0.11
е	5.44	BSC	0.2	1 BSC
L	19.82	20.22	0.78	0.80
L1	-	4.30	-	0.17
ΦΡ	3.40	3.80	0.13	0.15
ΦP1	-	7.30	-	0.29
S	6.15BSC		0.24	4 BSC



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